

67,200-646
2001-0335

ABSTRACT

0041 A method for preventing a photo-induced chemical attack on a copper containing dielectric material including providing a copper or copper oxide containing dielectric material having an exposed copper containing surface; providing an acidic cleaning solution for contacting the exposed copper containing surface; and, shielding the exposed copper containing surface to substantially block incident light from impacting the exposed copper containing surface while contacting the exposed copper containing surface with the cleaning solution.